



# SP B.1 ENEA activity in 2021-2022: Overview of GyM results

A. Uccello,

on behalf of A. Cremona, F. Ghezzi, M. Pedroni, E. Vassallo,  
G. Alberti, D. Dellasega, D. Vavassori, M. Passoni

**Beneficiary: ENEA**

**Linked Third Parties: ISTP-CNR Milano and Politecnico di Milano**



**POLITECNICO  
MILANO 1863**



This work has been carried out within the framework of the EUROfusion Consortium, funded by the European Union via the Euratom Research and Training Programme (Grant Agreement No 101052200 — EUROfusion). Views and opinions expressed are however those of the author(s) only and do not necessarily reflect those of the European Union or the European Commission. Neither the European Union nor the European Commission can be held responsible for them.

# Overview of GyM results



*PWIE.SP.B.1.T002.D002*

Role of roughness in sputtering process of W by GyM He plasma

Focus of  
this talk

Linked PWIE-SPs

**Sample production**

*PWIE-SP B.4.T-T002-D001*

W-based coatings with pre-defined properties (incl. SEM, AFM, TDS characterisation) produced for analyses and plasma experiments

**Modelling**

*PWIE-SP D.1.T-T002-D003*

Plasma background parameters of GyM for modelling of impurity migration experiments

*PWIE-SP D.3.T-T002-D002*

ERO2.0 simulations of dynamic morphology studies in GyM, ERO2.0 simulations of the transport of sputtered material in GyM, Global ERO2.0 modelling of erosion/deposition in AUG

Highlight talk  
G. Alberti

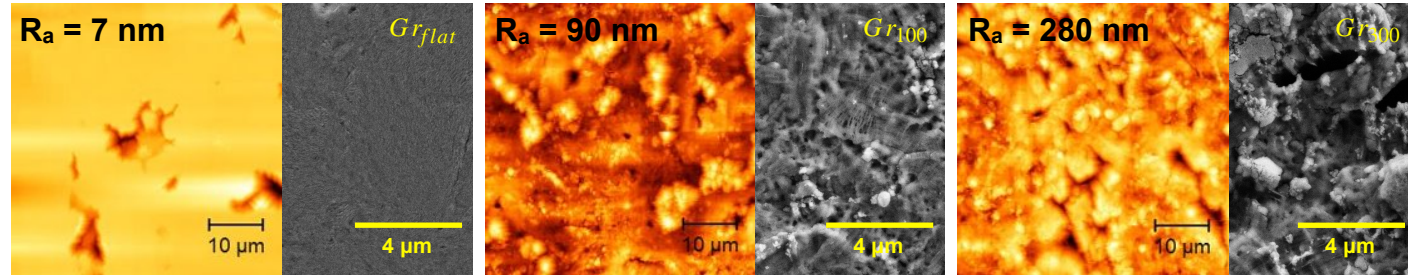
*All activities carried out in Milan in frame of collaboration between ISTP-CNR and Polimi*



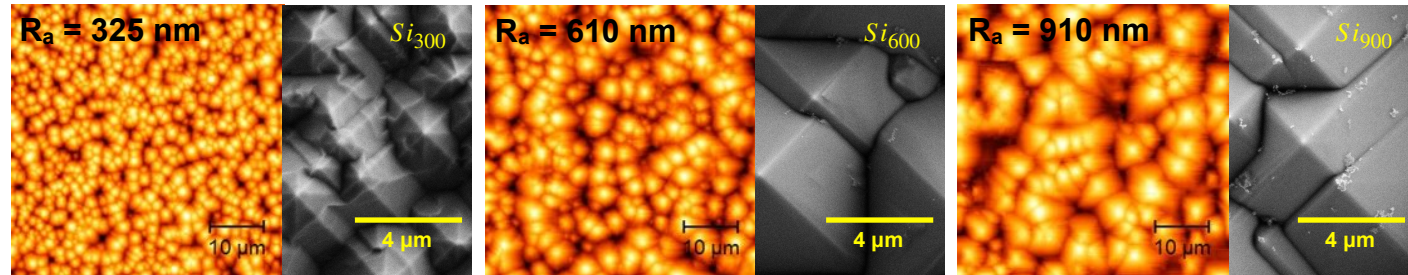
**W coatings** on top of **graphite** and **Si** substrates, from SP B.4 + **polished bulk W** ( $R_a \sim 10$  nm)

## Substrates (ISTP)

- Polished **graphite**
- Rough **graphite** substrates by plasma etching  
 $R_a \rightarrow 100, 300$  nm



- Flat **Si**,  $R_a < 1$  nm
- **Si** with pyramids by chemical etching  
 $R_a \rightarrow 300, 600, 900$  nm



**8 kinds of samples**



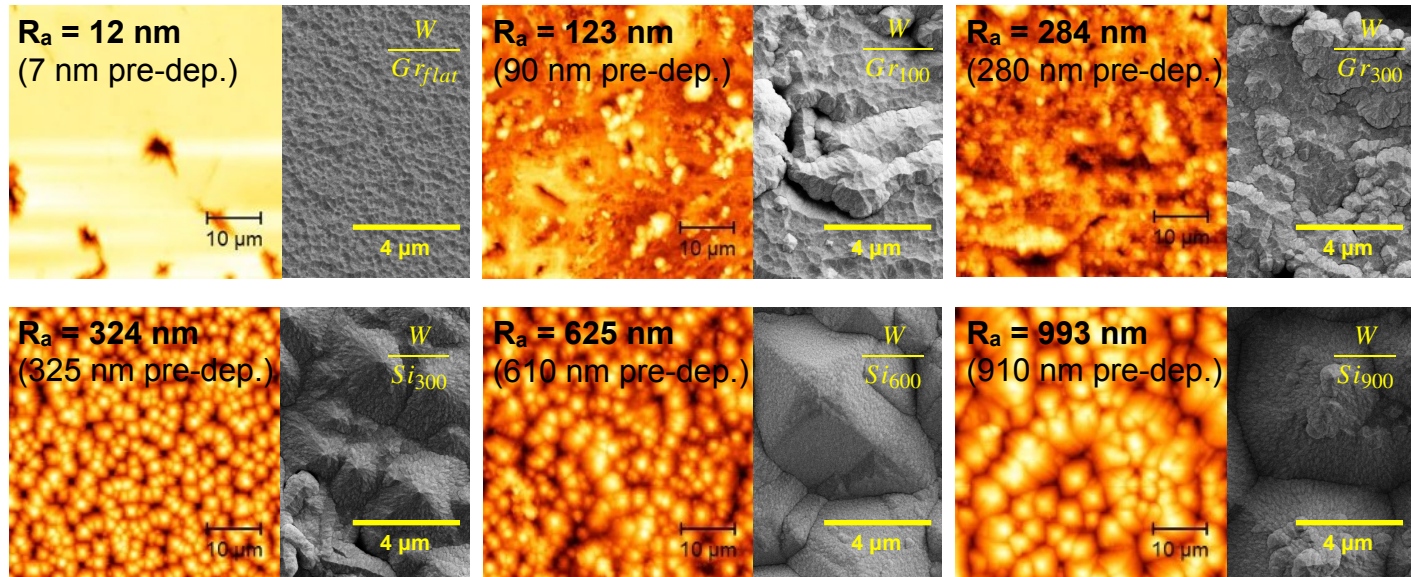
**W coatings** on top of **graphite** and **Si** substrates, from SP B.4 + **polished bulk W** ( $R_a \sim 10$  nm)

Substrates (ISTP)

+

500 nm compact **W film**

by HiPIMS (Polimi)



Side activity: *Study angular distribution of sputtered W particles from W/Si with Catcher-QCM setup of ÖAW*  
(C. Cupak SP B highlight talk, 17/10/22)



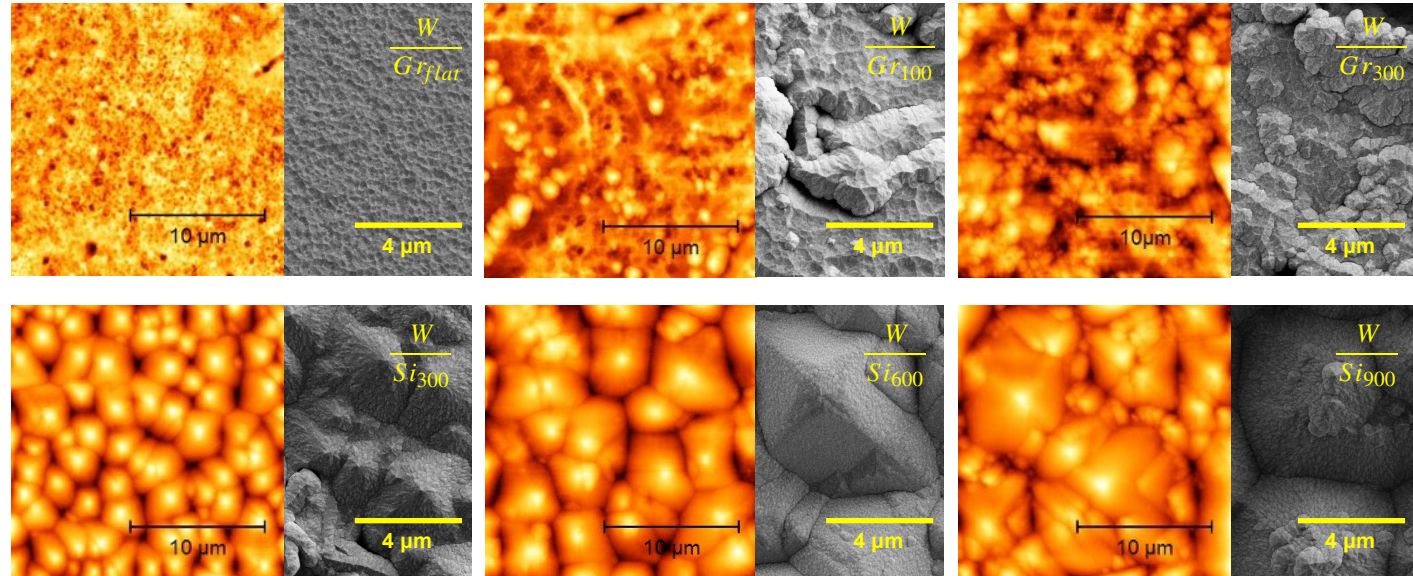
**W coatings** on top of **graphite** and **Si** substrates, from SP B.4 + **polished bulk W** ( $R_a \sim 10$  nm)

Substrates (ISTP)

+

500 nm compact **W film**

by HiPIMS (Polimi)



AFM images:  $20 \times 20 \mu\text{m}^2$  → ERO2.0 input to study erosion during plasma exposure  
**Polimi+ISTP** activity for SP D.3 (see G. Alberti SP D highlight talk, 19/10/22)

# Role of roughness in sputtering process of W by GyM He plasma

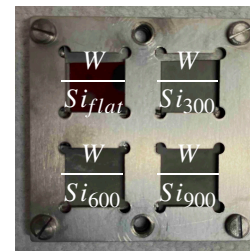


Exposure of W/Si samples: **6 He<sup>+</sup> energies @ 4.0e24 He<sup>+</sup> m<sup>-2</sup>**

**He<sup>+</sup> energy [eV]** 30 | 80 | 150 | 200 | 250 + 350

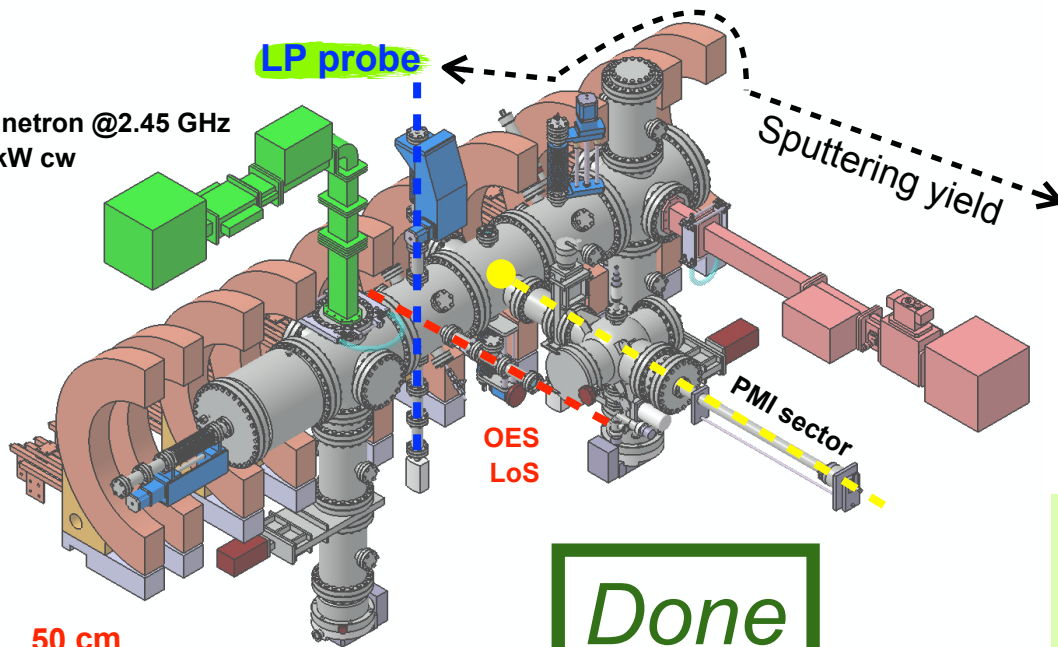
Sputtering E<sub>th</sub> of W<sub>bulk</sub> by He<sup>+</sup> ~110 eV

[W. Eckstein, et al., IPP 9/82 Sputtering data]



T<sub>holder</sub> ≤ 150°C

Magnetron @2.45 GHz  
3.0 kW cw



**Done**

## Before and after exposures

- **Weighing** → erosion by using balance @ CNR-Mi
- **AFM** → topography evolution @ ISTP
- **SEM** → morphology evolution @ Polimi

Data for benchmarking with SOLPS-ITER and ERO2.0 modelling efforts **Polimi+ISTP** SP D.1 & D.3

# Role of roughness in sputtering process of W by GyM He plasma

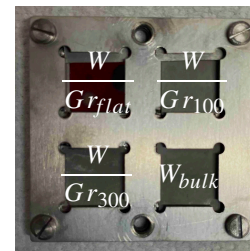


Exposure of W/Gr + W<sub>bulk</sub> samples: **5 He<sup>+</sup> energies @ 4.0e24 He<sup>+</sup> m<sup>-2</sup>**

He <sup>+</sup> energy [eV]	30	80	150	200	250
-----------------------------	----	----	-----	-----	-----

Sputtering E<sub>th</sub> of W<sub>bulk</sub> by He<sup>+</sup> ~110 eV

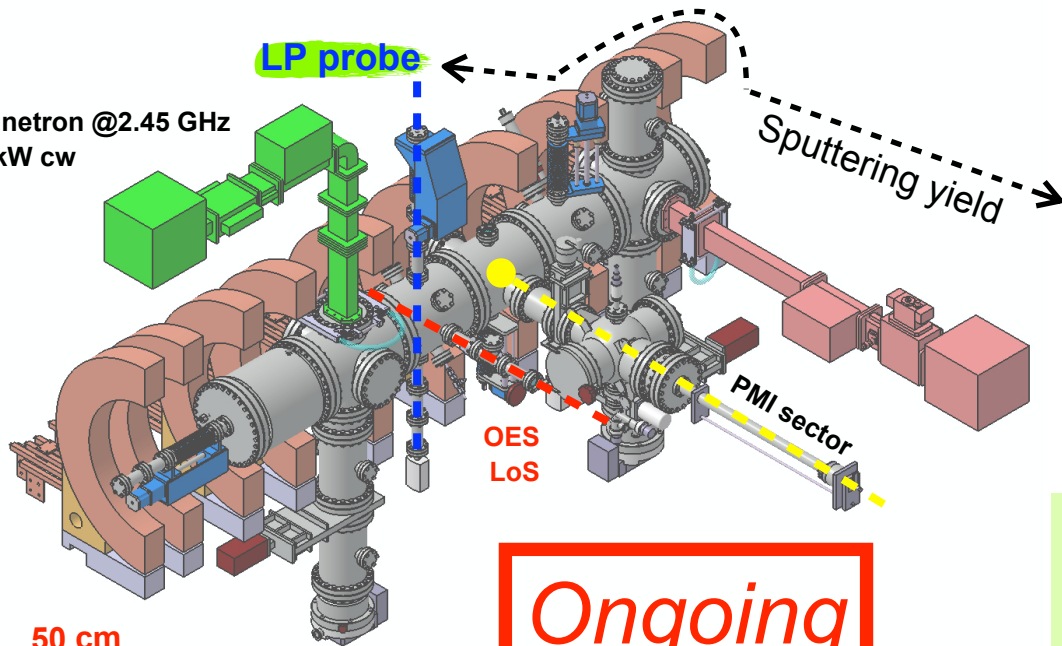
[W. Eckstein, et al., IPP 9/82 Sputtering data]



1 cm

LP probe

Magnetron @2.45 GHz  
3.0 kW cw



50 cm

Ongoing

Sputtering yield

## Before and after exposures

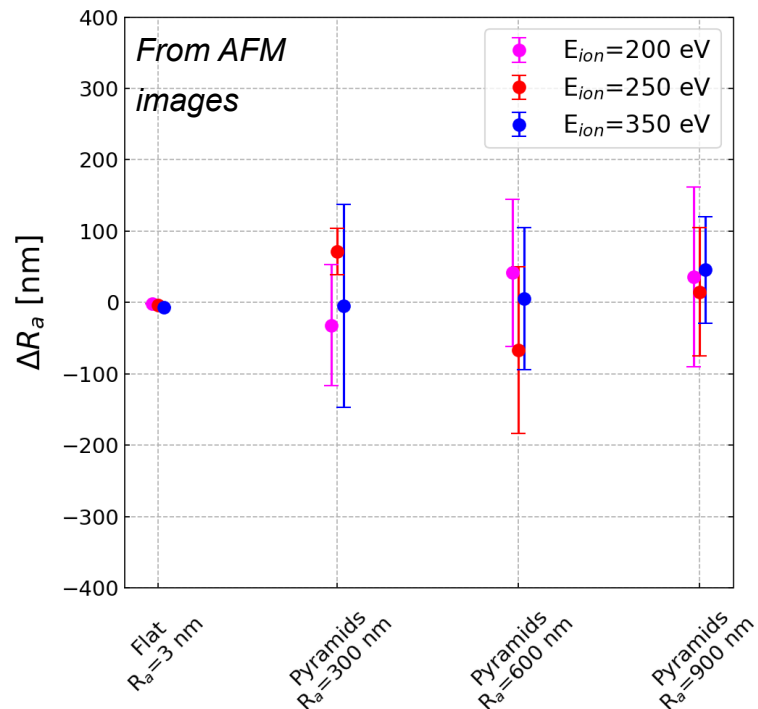
- **Weighing** → erosion by using balance @ CNR-Mi
- **AFM** → topography evolution @ ISTP
- **SEM** → morphology evolution @ Polimi
- **FIB marking** → W<sub>bulk</sub> → erosion @ FZJ

Data for benchmarking with SOLPS-ITER and ERO2.0 modelling efforts **Polimi+ISTP** SP D.1 & D.3

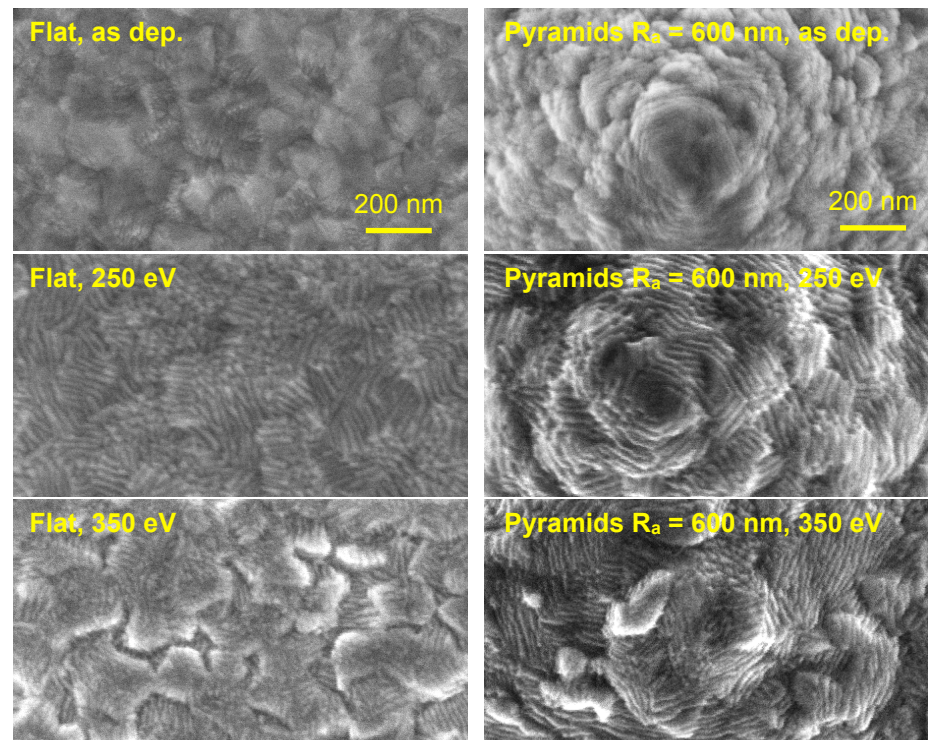
# Role of roughness in sputtering process of W by GyM He plasma



Samples topography did not significantly change after exposures



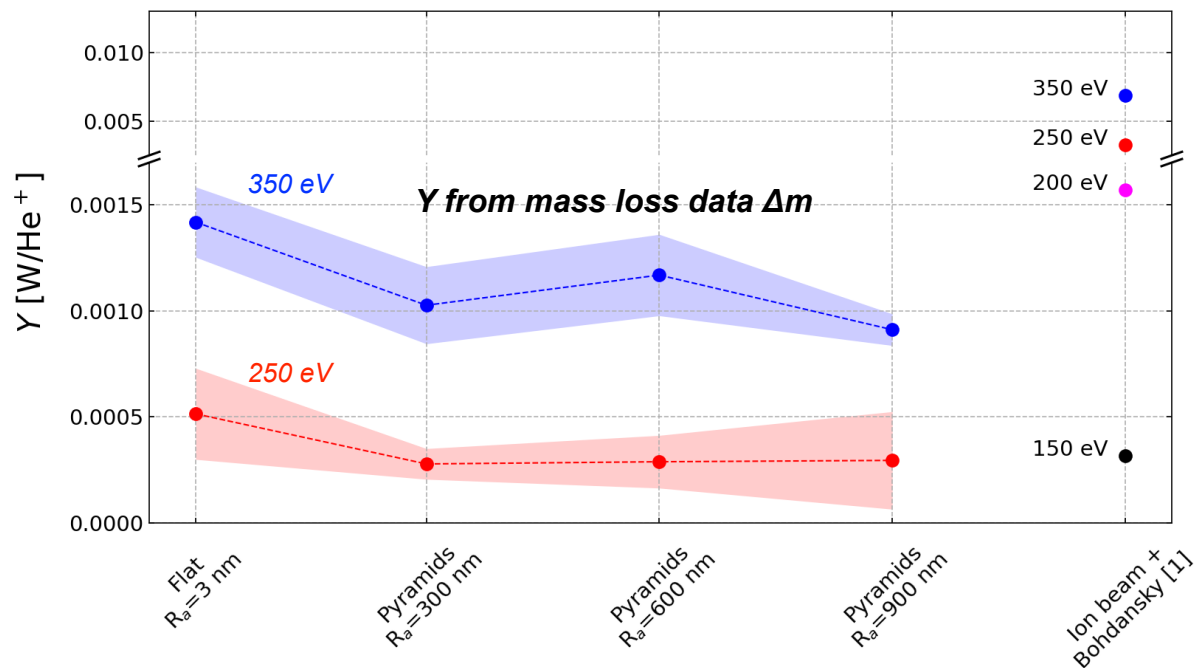
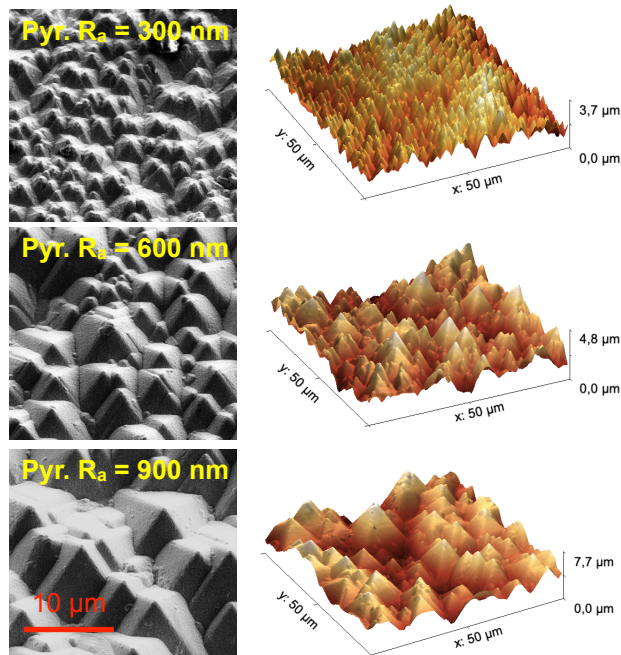
All types of W/Si: ripple nanostructures for  $E_{ion} \geq 250$  eV



No significant topography and morphology modifications → determination of quasi-static sputtering yield  $Y$

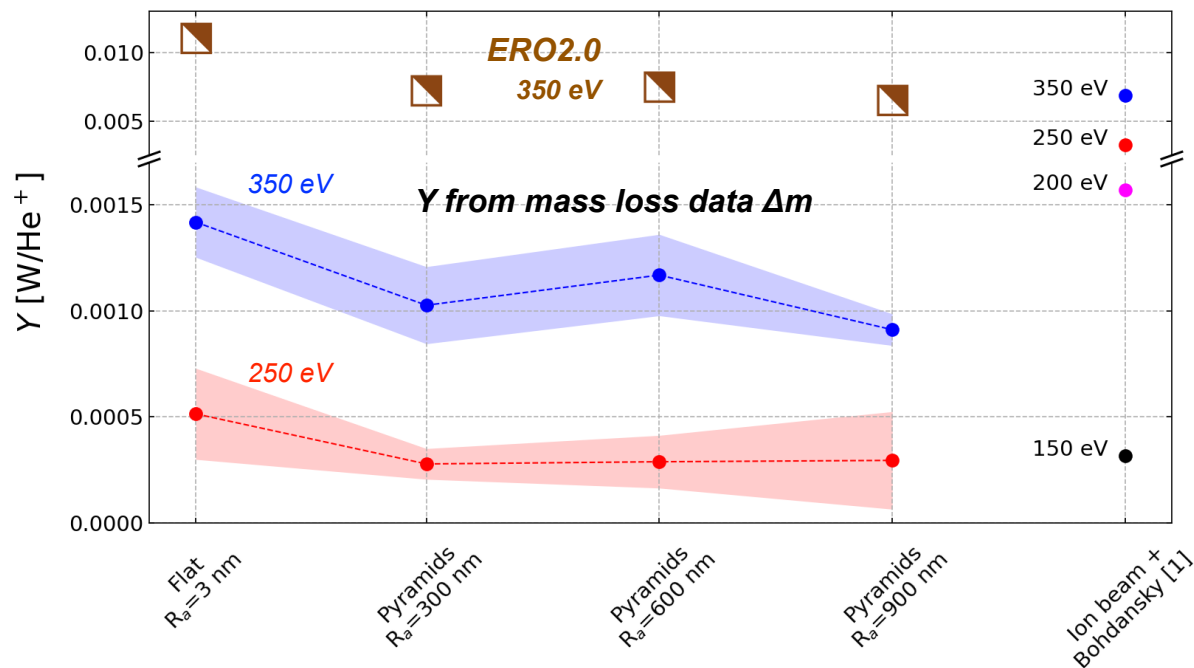
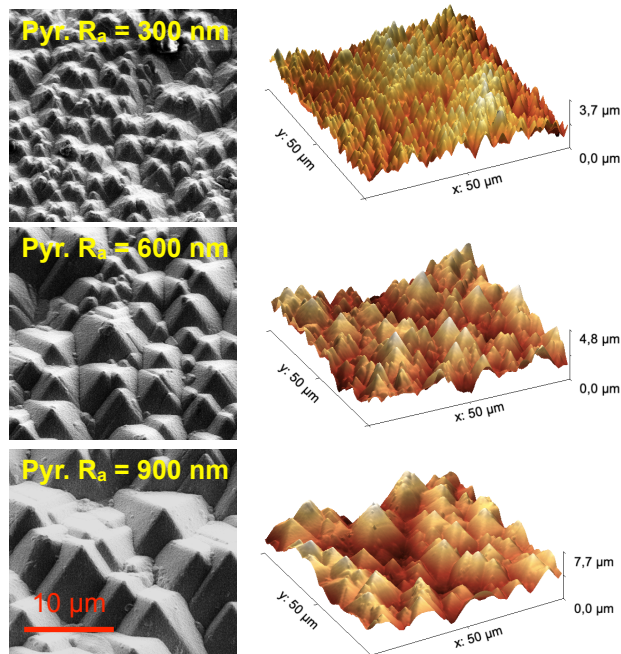


# Role of roughness in sputtering process of W by GyM He plasma



- No erosion for  $E_{ion} \leq 200$  eV
- For  $E_{ion} \geq 250$  eV  $\rightarrow Y_{Flat, \Delta m} > Y_{Pyramids, \Delta m}$
- $Y_{\Delta m} \ll Y_{Ion} \rightarrow$  similar to what was observed in other LPD experiments [2]. In [2], It was speculated that He atoms on surface, due to He incoming flux, shield W lattice atoms reducing their sputtering probability

# Role of roughness in sputtering process of W by GyM He plasma



- No erosion for  $E_{ion} \leq 200$  eV
- For  $E_{ion} \geq 250$  eV  $\rightarrow Y_{Flat, \Delta m} > Y_{Pyramids, \Delta m}$
- $Y_{\Delta m} \ll Y_{Ion} \rightarrow$  similar to what was observed in other LPD experiments [2]. In [2], It was speculated that He atoms on surface, due to He incoming flux, shield W lattice atoms reducing their sputtering probability
  - This potentially explains  $\rightarrow Y_{\Delta m} \ll Y_{ERO}$  at 350 eV since sputtering yields as input to ERO2.0 refer to pure W surface

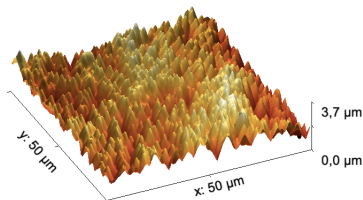
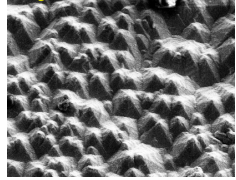
[1] W. Eckstein, et al., IPP 9/82 Sputtering data

[2] R. P. Doerner, Scr. Mater. 143 (2018) 137-141

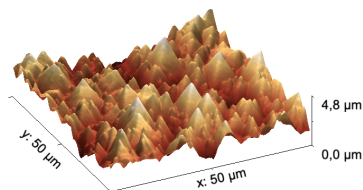
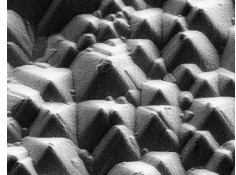
# Role of roughness in sputtering process of W by GyM He plasma



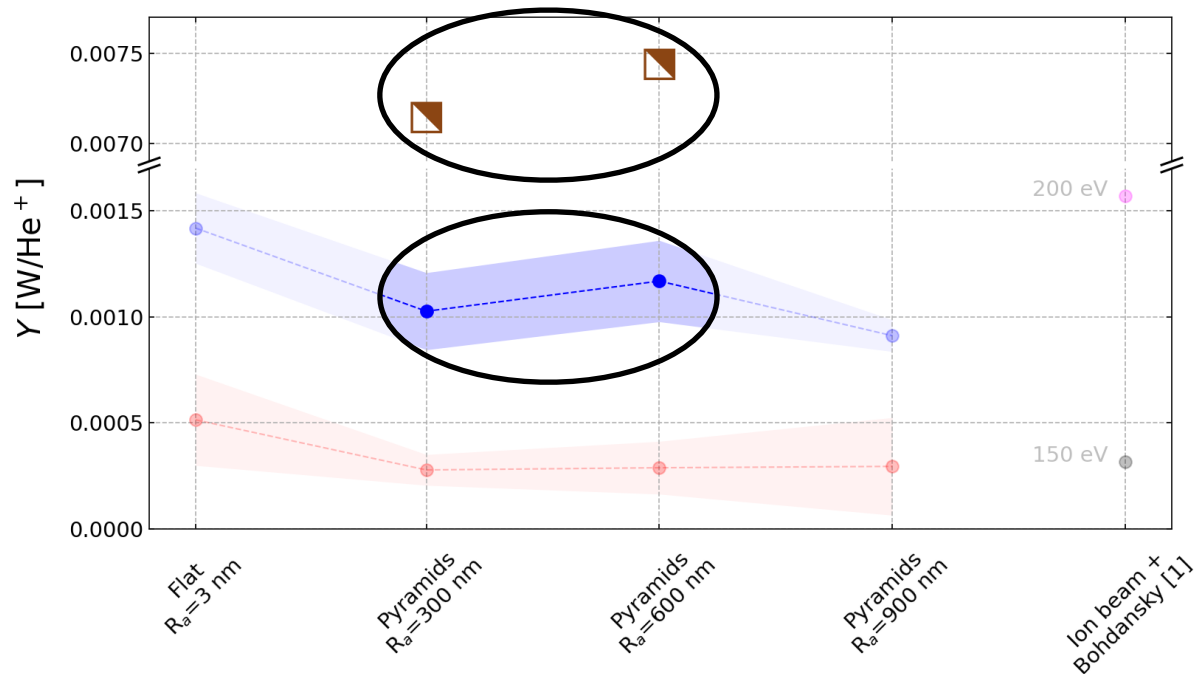
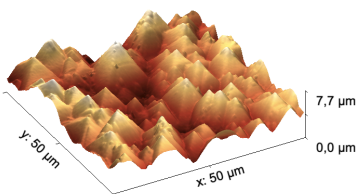
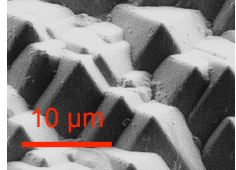
Pyr.  $R_a = 300$  nm



Pyr.  $R_a = 600$  nm



Pyr.  $R_a = 900$  nm



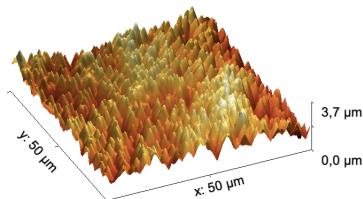
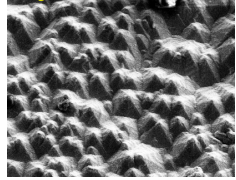
- **Non-monotonous behaviour** of  $Y_{\Delta m}$  and  $Y_{ERO}$  at  $E_{ion} = 350$  eV if  $R_a$  is used for characterising surfaces
- What happen if surfaces characterised by **mean value of surface inclination angle distribution**,  $\delta_m$ , as suggested in [2]?

[1] W. Eckstein, et al., IPP 9/82 Sputtering data

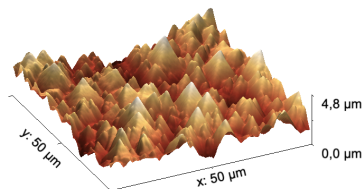
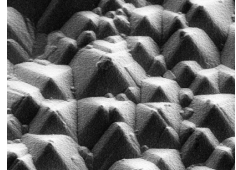
[2] C. Cupak, et al., Appl. Surf. Sci. 570 (2021) 151204



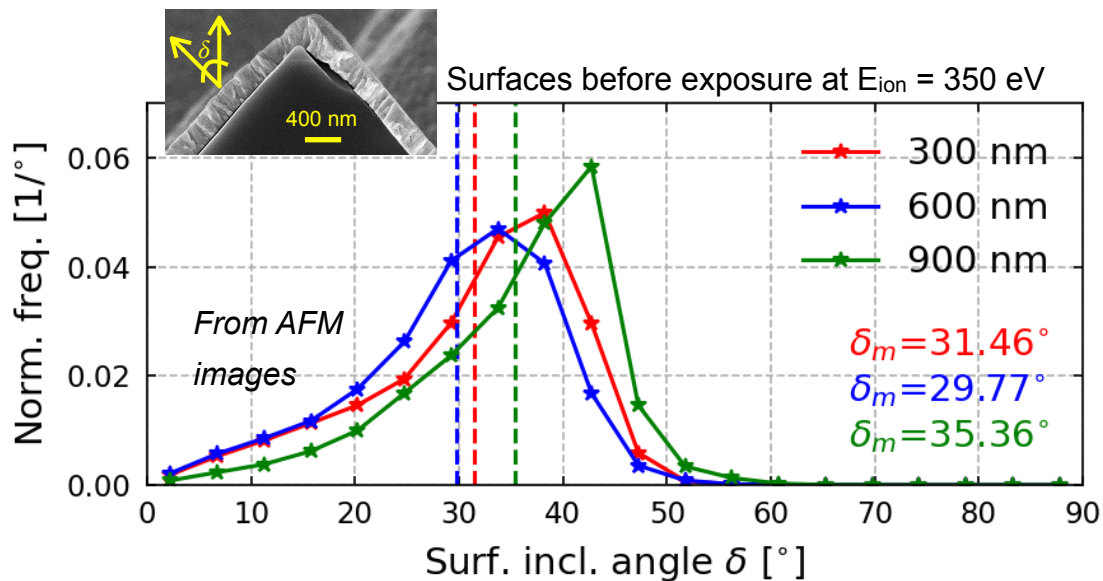
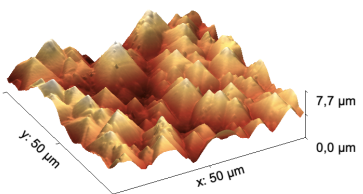
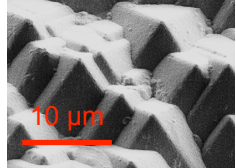
Pyr.  $R_a = 300$  nm



Pyr.  $R_a = 600$  nm



Pyr.  $R_a = 900$  nm



- **Non-monotonous behaviour** of  $Y_{\Delta m}$  and  $Y_{ERO}$  at  $E_{ion} = 350$  eV if  $R_a$  is used for characterising surfaces
- What happen if surfaces characterised by **mean value of surface inclination angle distribution**,  $\delta_m$ , as suggested in [2]?

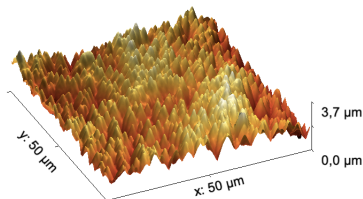
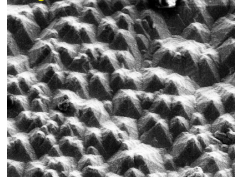
[1] W. Eckstein, et al., IPP 9/82 Sputtering data

[2] C. Cupak, et al., Appl. Surf. Sci. 570 (2021) 151204

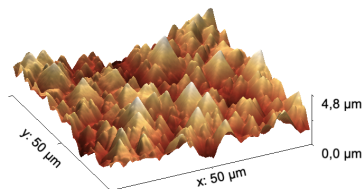
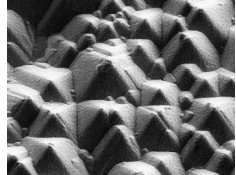
# Role of roughness in sputtering process of W by GyM He plasma



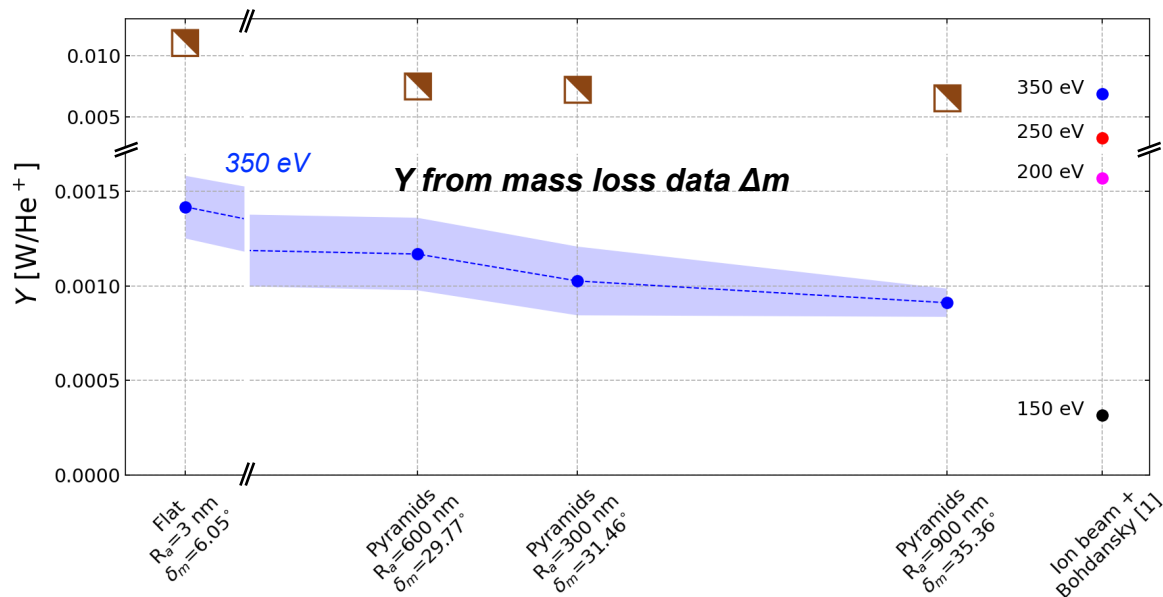
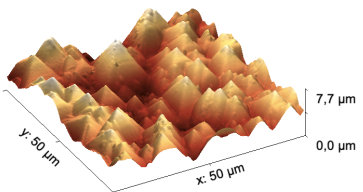
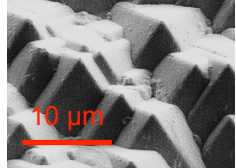
Pyr.  $R_a = 300$  nm



Pyr.  $R_a = 600$  nm



Pyr.  $R_a = 900$  nm



- **Non-monotonous behaviour** of  $Y_{\Delta m}$  and  $Y_{ERO}$  at  $E_{ion} = 350$  eV if  $R_a$  is used for characterising surfaces
- What happen if surfaces characterised by **mean value of surface inclination angle distribution,  $\delta_m$** , as suggested in [2]?



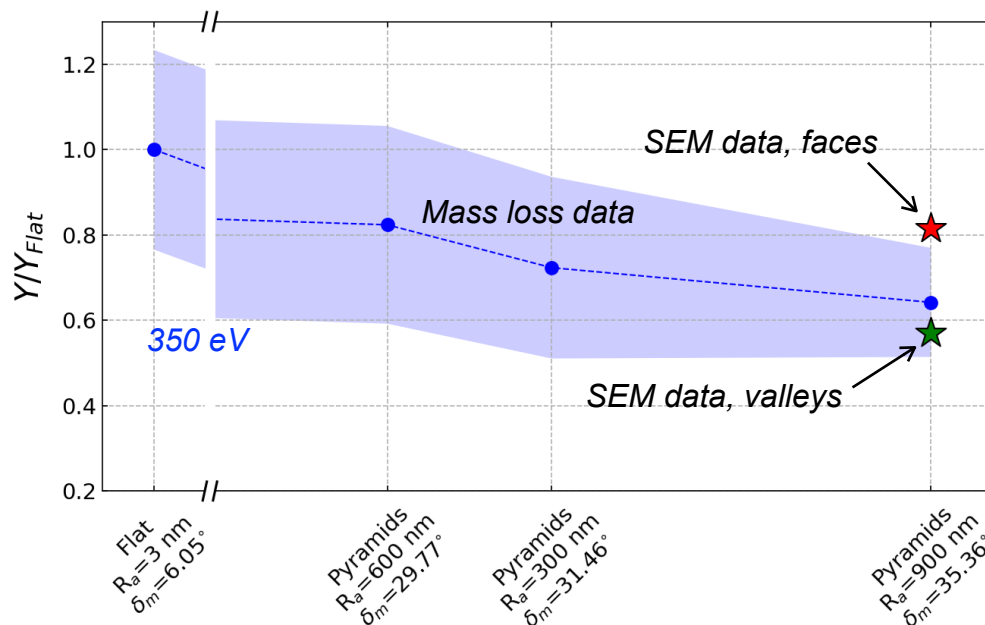
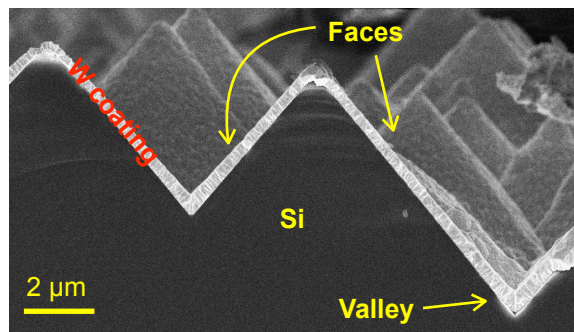
[1] W. Eckstein, et al., IPP 9/82 Sputtering data

[2] C. Cupak, et al., Appl. Surf. Sci. 570 (2021) 151204

# Role of roughness in sputtering process of W by GyM He plasma



Erosion data also from SEM cs images: statistical analysis of W coating thickness loss ( $\Delta s$ )



Preliminary results

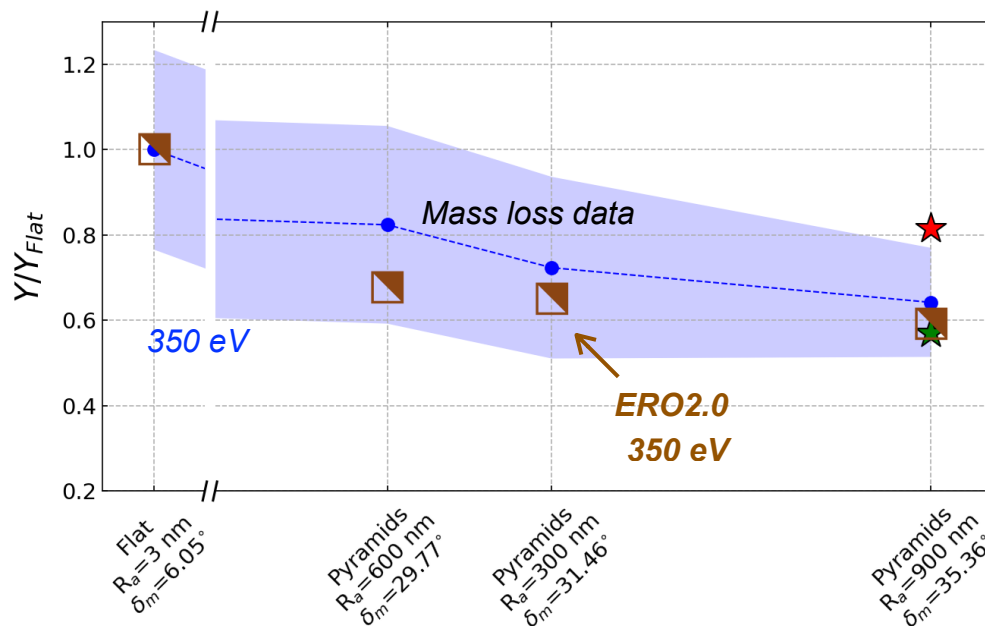
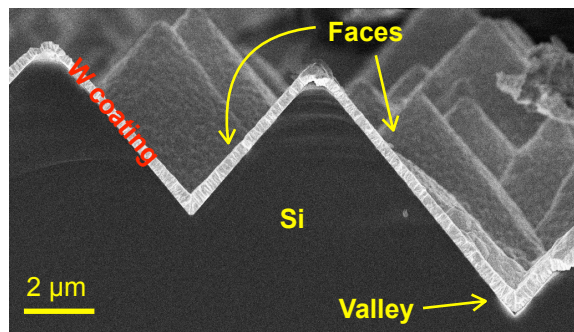
350 eV	Flat	Pyr. $R_a = 900$ nm	
		Faces	Valleys
$\overline{\Delta s}$ [nm]	60.7	49.4	34.6
$\sigma_{\Delta s}$ [nm]	17.0	29.9	35.9

- $\Delta S_{Flat} > \Delta S_{Pyramids}$ , in agreement with  $\Delta m$  data
- $\Delta S_{Pyr.,Faces} > \Delta S_{Pyr.,Valleys}$  → deposition of sputtered particles from faces in valleys?
- Further work needed to reduce  $\sigma_{\Delta s}$

# Role of roughness in sputtering process of W by GyM He plasma



Erosion data also from SEM cs images: statistical analysis of W coating thickness loss ( $\Delta s$ )



Preliminary results

350 eV	Flat	Pyr. $R_a = 900$ nm	
		Faces	Valleys
$\overline{\Delta s}$ [nm]	60.7	49.4	34.6
$\sigma_{\Delta s}$ [nm]	17.0	29.9	35.9

- $Y_{Pyr.}/Y_{Flat}$  from **ERO2.0**, **mass** and **thickness** loss measurements are consistent
- **Calibration** of sputtering yields as input to **ERO2.0** with  $Y_{Flat,\Delta m}$  to quantitatively catch  $Y_{Pyr.,\Delta m}$ ?





- Graphite substrates with irregular surface and silicon substrates with pyramids were covered with 500 nm compact W coatings
- W/Si samples were exposed to He plasma at 6 He<sup>+</sup> energies @ 4.0e24 He<sup>+</sup> m<sup>-2</sup>
- W/Si quasi-static Y was evaluated from mass and thickness loss measurements
- No erosion for E<sub>ion</sub> ≤ 200 eV and for E<sub>ion</sub> ≥ 250 eV → Y<sub>Flat</sub> > Y<sub>Pyramids</sub>
- Mean value of surface inclination angle distribution good parameter to characterise surfaces
- Y<sub>Δm</sub> ≪ Y<sub>Ion</sub> → similar to what was observed in other LPD experiments
- Y<sub>Δm</sub> ≪ Y<sub>ERO</sub> at 350 eV but Y<sub>Pyr./Flat</sub> agrees → calibration of sputtering yields as input to ERO2.0 with Y<sub>Flat,Δm</sub> to quantitatively catch Y<sub>Pyr.,Δm</sub>? (see SP D highlight talk of G. Alberti)
- W/Gr + W<sub>bulk</sub> exposure, characterisation and comparison with W/Si by year-end



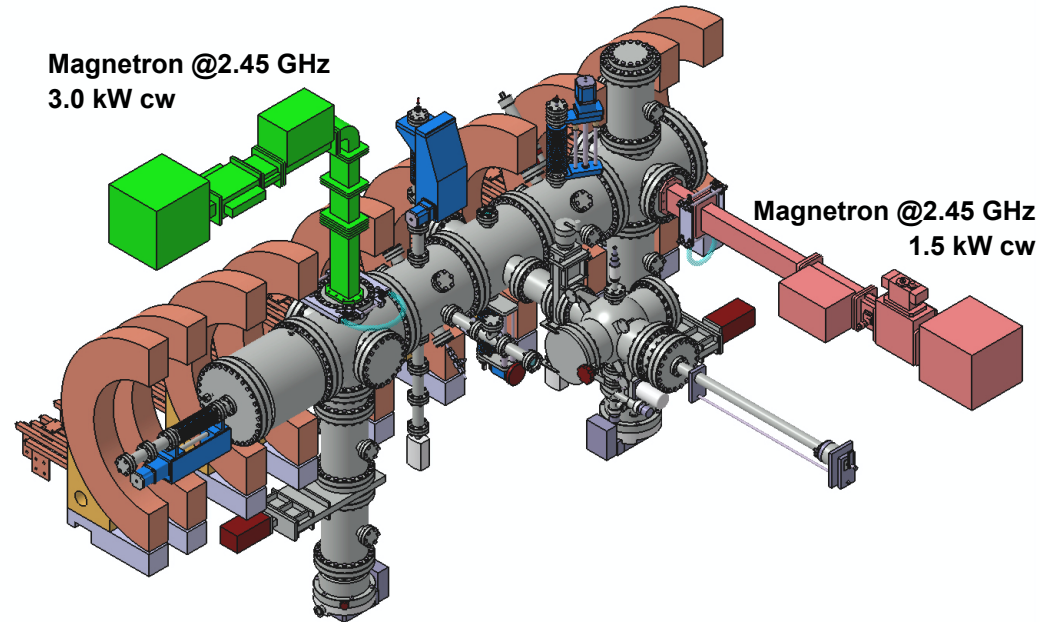
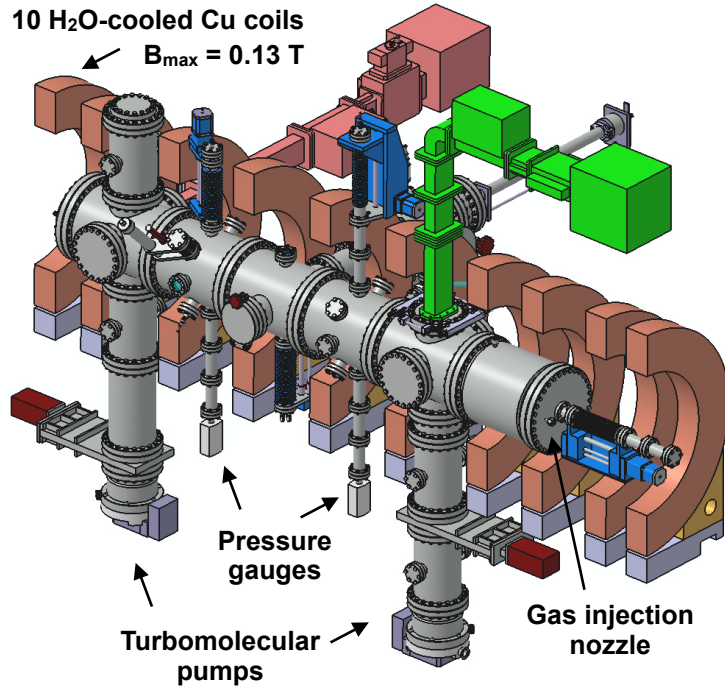


Thank you!

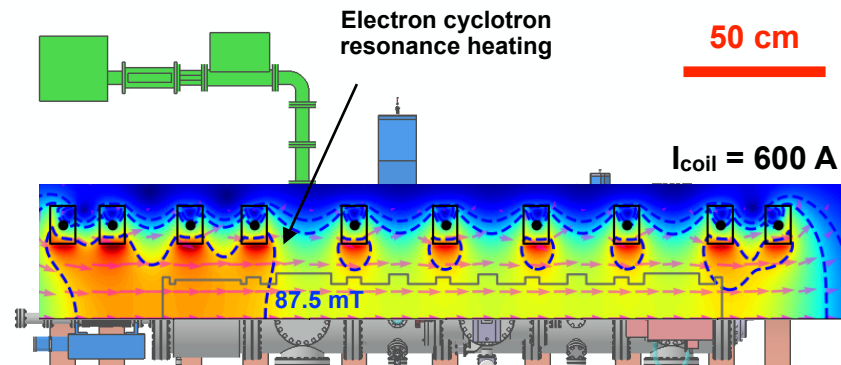
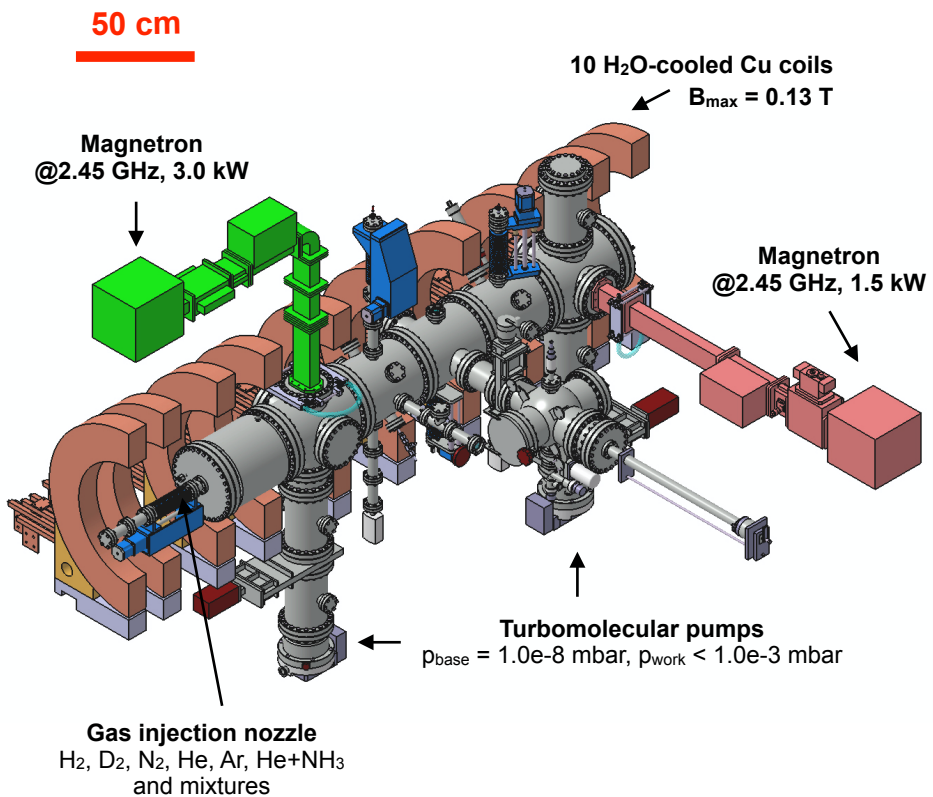
# GyM linear plasma device @ ISTEP-CNR Milano



Vacuum vessel	Stainless steel (SS): L = 2.11 m, $\varnothing$ = 25 cm (optional: SS liner with W coating)
Pumping system	2 turbopumps: $p_{\text{base}} = 1\text{E-}8$ mbar, $p_{\text{work}} < 1\text{E-}3$ mbar
Working gas	H <sub>2</sub> , D <sub>2</sub> , N <sub>2</sub> , He, Ar, He+NH <sub>3</sub> and mixtures



# Linear plasma device GyM @ ISTP-CNR Milan



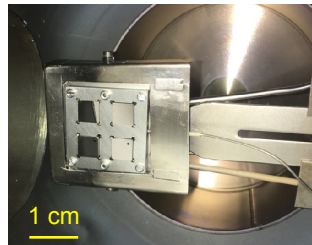
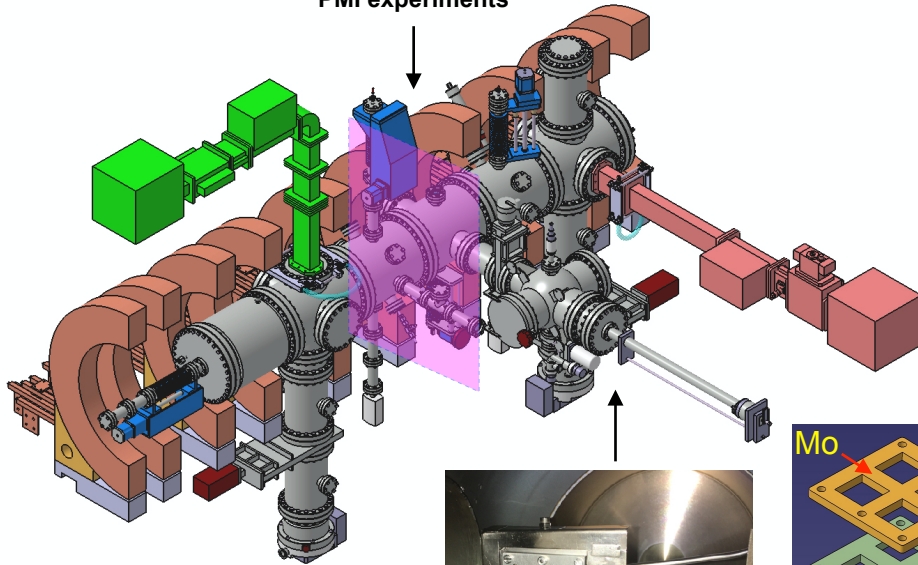
$t_{\text{pulse}}$ [s]	Steady state
$\varnothing_{\text{plasma}}$ [cm]	20
$n_e$ [m <sup>-3</sup> ]	up to 10 <sup>17</sup>
$T_e$ [eV]	3-15
$T_i$ [eV]	<0.1
$\Gamma$ [ions m <sup>-2</sup> s <sup>-1</sup> ]	up to 10 <sup>21</sup>
$\Phi_{\text{max}}$ [ions m <sup>-2</sup> ]	10 <sup>25</sup> (7 h)

# Linear plasma device GyM @ ISTP-CNR Milan

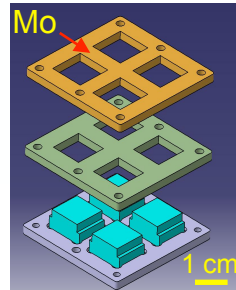


50 cm

PMI experiments



Sample exposure system + bolometry

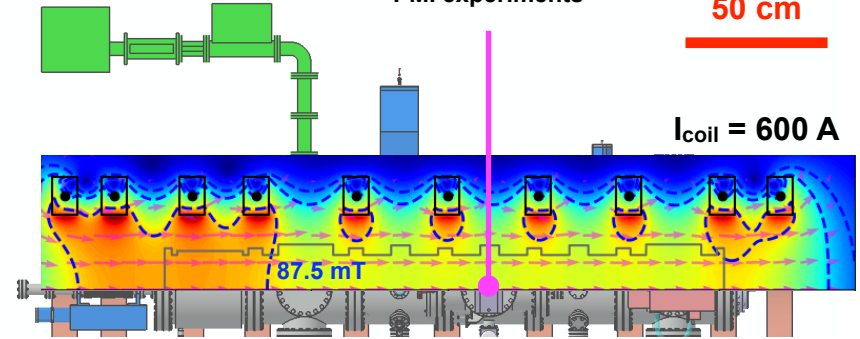


## Sample geometry

PSI-2 standard  
square slab  
 $l = 12 \text{ mm} - 0.2 \text{ mm}$   
 $s \leq 3 \text{ mm}$

PMI experiments

50 cm



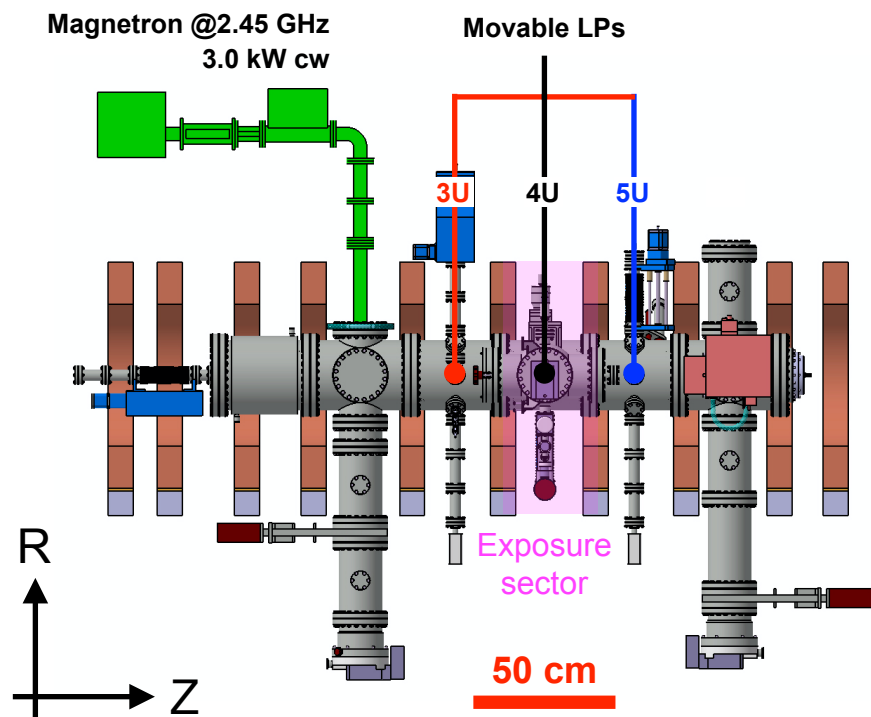
$I_{\text{coil}} = 600 \text{ A}$

$t_{\text{pulse}} [\text{s}]$	Steady state
$\varnothing_{\text{plasma}} [\text{cm}]$	20
$n_e [\text{m}^{-3}]$	up to $10^{17}$
$T_e [\text{eV}]$	3-15
$T_i [\text{eV}]$	<0.1
$\Gamma [\text{ions m}^{-2}\text{s}^{-1}]$	up to $10^{21}$
$\Phi_{\text{max}} [\text{ions m}^{-2}]$	$10^{25}$ (7 h)
Incident ion energy [eV]	20-400

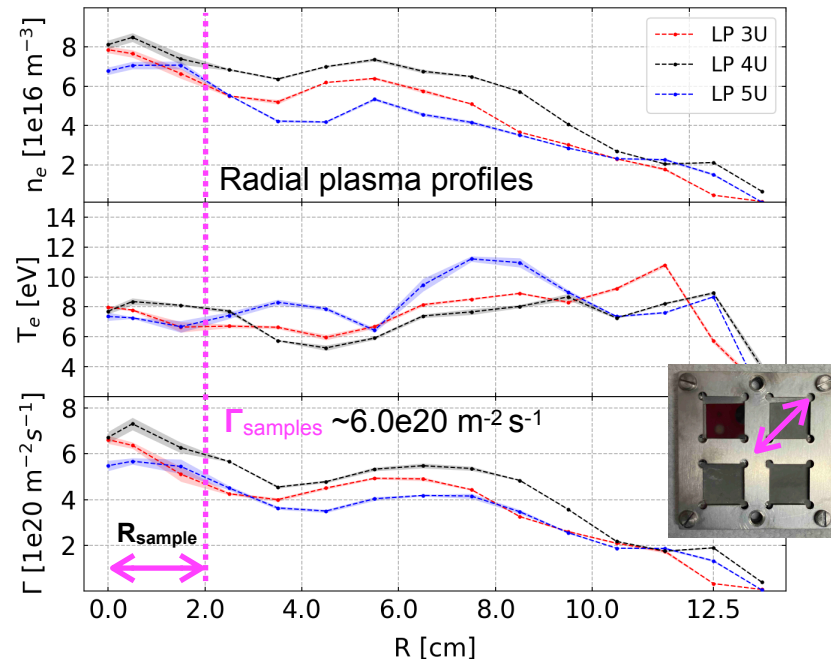
# Characterisation of GyM He plasma by LPs and OES



- Optimisation of experimental conditions to obtain **max** and **homogeneous**  $\Gamma_{He^+}$  on samples
- Provide full set of data for validation of SOLPS-ITER results of **Polimi+ISTP** for SP D.1 & 3



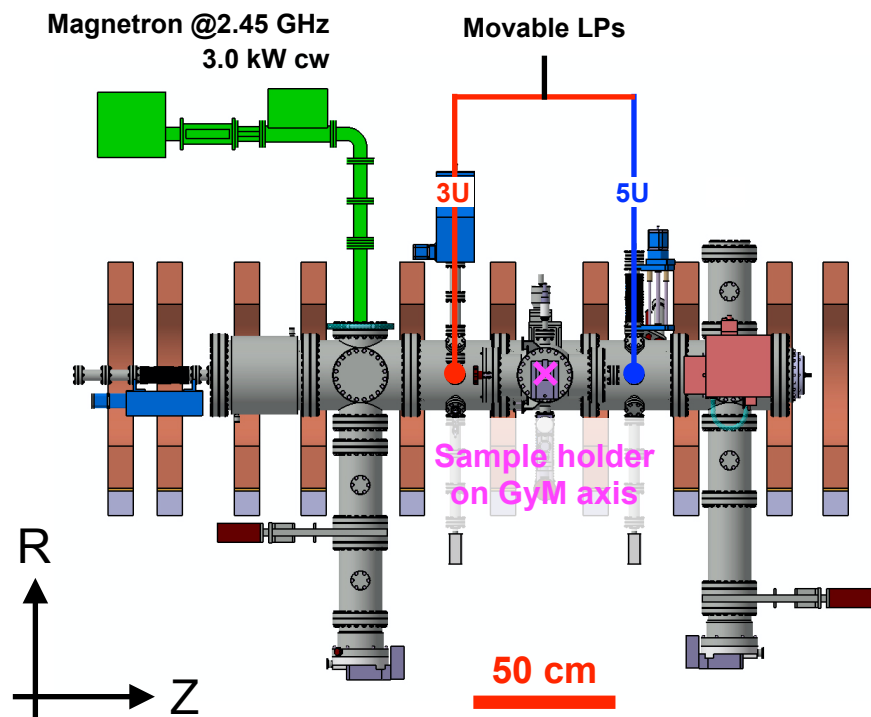
Opt. cond.  $\rightarrow I_{coil} = 600$  A,  $P_{source} = 1.2$  kW,  $p = 0.10$  Pa



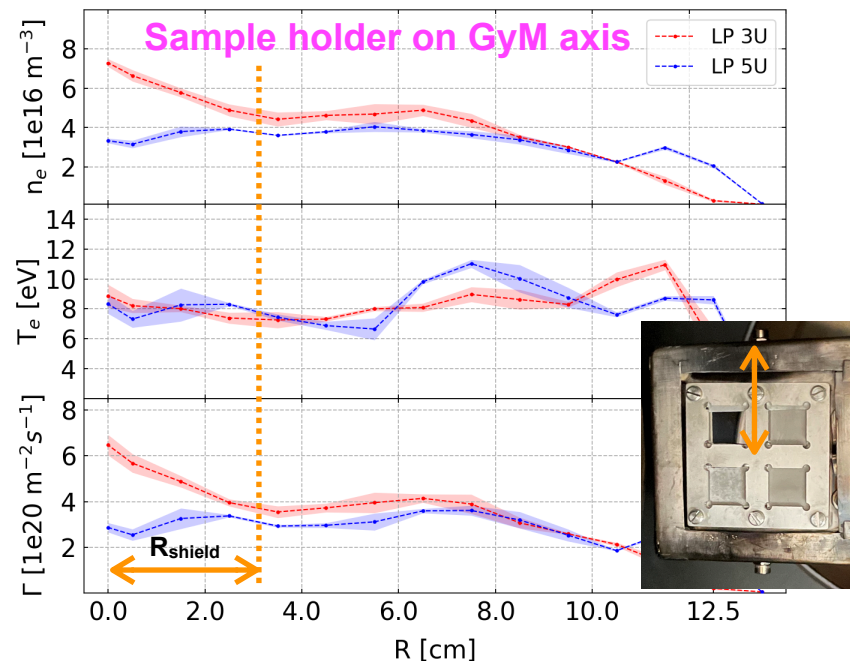
# Characterisation of GyM He plasma by LPs and OES



- Optimisation of experimental conditions to obtain **max** and **homogeneous**  $\Gamma_{He^+}$  on samples
- Provide full set of data for validation of SOLPS-ITER results of **Polimi+ISTP** for SP D.1 & 3



Opt. cond.  $\rightarrow I_{coil} = 600$  A,  $P_{source} = 1.2$  kW,  $p = 0.10$  Pa

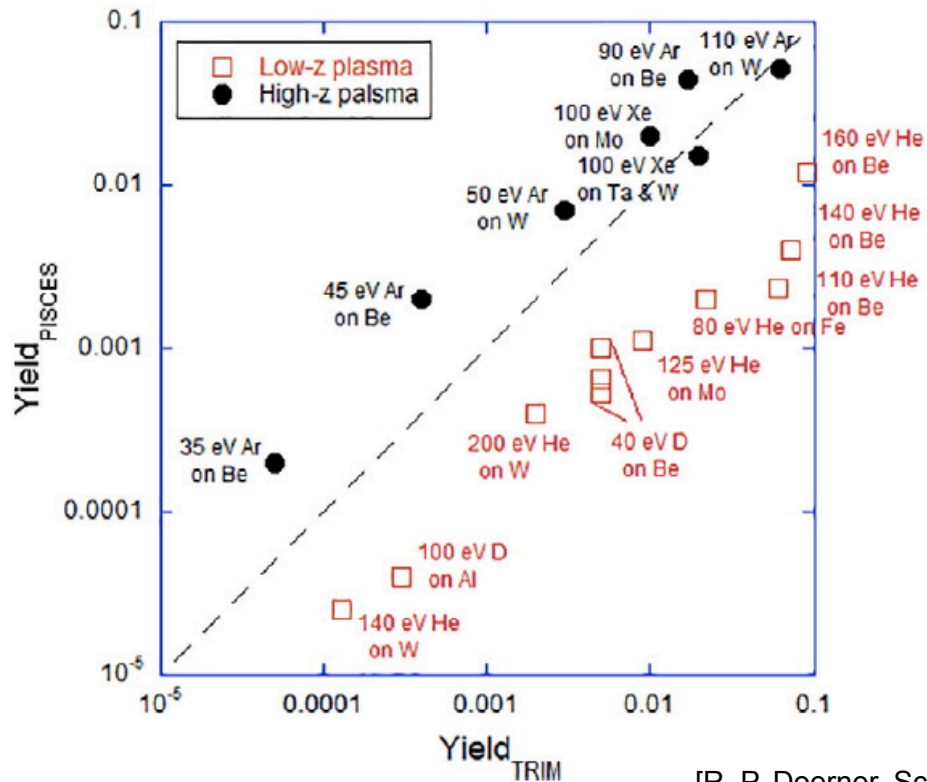




*Study angular distribution of sputtered W particles from W/Si<sub>py</sub> with Catcher-QCM setup of ÖAW*

[B. M. Berger, et al., NIM-B 406(2017)533-7]

- 2 **Si** substrates with pyramids and  $R_a = 500 - 600$  nm (ISTP) ✓
- 2 **Si** substrates with pyramids and  $R_a = 900 - 1000$  nm (ISTP) ✓
- 2 **Si** flat substrates ✓
- Deposition of compact **W coatings** (Polimi) ✓
- AFM analysis of W/Si<sub>py</sub> (ISTP) ✓
- Shipping to Wien ✓



[R. P. Doerner, Scr. Mater. 143 (2018) 137-141]